



Model SPL15T

No. of Drive for ring	: 2
Platen size	: 15"(Ø380mm)
Platen drive Motor	: 0.4 Kw
Table speed	: 10-60 rpm
Drive ring speed	: 18-280 rpm
Size of correction Ring	: 5.5" I.D.
Footprint	: 22"x30"x23"

Automatic Desktop type Precision Lapping Machine for R & D or Small Lot

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Automatic Precision Lapping Machine
Model SPL15T

FEATURES

Model SPL15T is designed to precision Lap semiconductor materials such as silicon, carbide, ceramics, brittle materials, and metals. Duplicate lapping stations are used in the desk top model which is compact enough to fit on a standard workbench, while operation is cost effective.

SPECIFICATIONS

Correction ring (Alumina ceramics)	I.D. 5.57" x O.D. 7" (141.5x178mm)
Drive unit for correction ring	2
Speed	18 - 280 rpm
Motor	25 W
Lapping table (Platen)	1 platen
Diameter	15" (Ø380 mm)
Speed	10 - 60 rpm
Type of Bearing	Ball bearing
Motor	0.4 Kw AC
Material of table	SUS 420 (Alumina ceramics is Option)
Slurry supply system	Micro Tube Pump
Slurry stirrer unit	Magnetic stirrer unit
Slurry Tank capacity	2 liters
Waste vessel	10 liters
Utility for electricity	3P, 200V, 10A
Footprint (L x W x H)	22" x 30" x 23" (560 x 750 x 580 mm)

Specifications subject to change without notice.